# PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Xi-Wei Lin	09/06/2006
Victor Moroz	09/06/2006
Dipankar Pramanik	09/06/2006

## **RECEIVING PARTY DATA**

Name:	Synopsys, Inc.	
Street Address:	700 E. Middlefield Road	
City:	Mountain View	
State/Country:	CALIFORNIA	
Postal Code:	94043	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11470978

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	SYNP 0861-1/WSW
NAME OF SUBMITTER:	Warren S. Wolfeld

Total Attachments: 2

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PATENT REEL: 018218 FRAME: 0452

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PATENT REEL: 018218 FRAME: 0453 Attorney Docket SYNP 0861-1

## JOINT TO CORPORATE ASSIGNMENT

WHEREAS, the undersigned,

- (1) Xi-Wei Lin 5155 Earle Street Fremont, CA 94536
- (2) Victor Moroz 12099 Atrium Drive Saratoga, CA 95070
- (3) Dipankar Pramanik 12667 Cheverly Court Saratoga, CA 95070

hereinafter termed "Inventors", have invented certain new and useful improvements in

# METHOD OF CORRELATING SILICON STRESS TO DEVICE INSTANCE PARAMETERS FOR CIRCUIT SIMULATION

and are filing such an application herewith, and have executed an oath or declaration of inventorship for such application on:

(hereinafter termed "application"); and

WHEREAS Synopsys, Inc., a corporation of Delaware, having a place of business at 700 E. Middlefield Road, Mountain View, California 94043-4033 (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

- 1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignce the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.
- 2. Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in

## Attorney Docket SYNP 0861-1

the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

- 3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.
- Said Inventors hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, said Inventors have executed and delivered this instrument to said Assignee as of the dates written below.

Signed: